# Low V<sub>CE(sat)</sub> Transistor, NPN, 60 V, 6.0 A

ON Semiconductor's e<sup>2</sup>PowerEdge family of low V<sub>CE(sat)</sub> transistors are surface mount devices featuring ultra low saturation voltage (V<sub>CE(sat)</sub>) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical applications are DC-DC converters and power management in portable and battery powered products such as cellular and cordless phones, PDAs, computers, printers, digital cameras and MP3 players. Other applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e<sup>2</sup>PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

#### Features

- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant\*
- Complementary to NSS60600MZ4

#### MAXIMUM RATINGS (T<sub>A</sub> = 25°C)

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	V <sub>CEO</sub>	60	Vdc
Collector-Base Voltage	V <sub>CBO</sub>	100	Vdc
Emitter-Base Voltage	V <sub>EBO</sub>	6.0	Vdc
Collector Current – Continuous	Ι <sub>C</sub>	6.0	Α
Collector Current – Peak	I <sub>CM</sub>	12.0	А

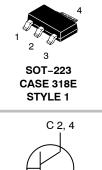
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



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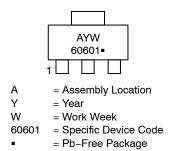
# **60 VOLTS, 6.0 AMPS 2.0 WATTS** NPN LOW V<sub>CE(sat)</sub> TRANSISTOR EQUIVALENT R<sub>DS(on)</sub> 50 mΩ



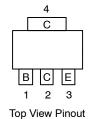


Schematic

#### MARKING DIAGRAM







#### **ORDERING INFORMATION** See detailed ordering and shipping information in the package

dimensions section on page 2 of this data sheet.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### **THERMAL CHARACTERISTICS**

Characteristic	Symbol	Max	Unit
Total Device Dissipation T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub> (Note 1)	800 6.5	mW mW/°C
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub> (Note 1)	155	°C/W
Total Device Dissipation T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub> (Note 2)	2 15.6	W mW/°C
Thermal Resistance, Junction-to-Ambient	R <sub>0JA</sub> (Note 2)	64	°C/W
Total Device Dissipation (Single Pulse < 10 sec.)	P <sub>Dsingle</sub> (Note 3)	710	mW
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	–55 to +150	°C

FR-4 @ 7.6 mm<sup>2</sup>, 1 oz. copper traces.
FR-4 @ 645 mm<sup>2</sup>, 1 oz. copper traces.

3. Thermal response.

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NSS60601MZ4T1G	SOT-223 (Pb-Free)	1,000 / Tape & Reel
NSV60601MZ4T1G*	SOT-223 (Pb-Free)	1,000 / Tape & Reel
NSS60601MZ4T3G	SOT-223 (Pb-Free)	4,000 / Tape & Reel
NSV60601MZ4T3G*	SOT-223 (Pb-Free)	4,000 / Tape & Reel

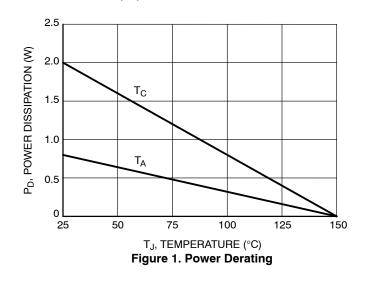
+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D. \*NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP

Capable.

# **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = $25^{\circ}$ C unless otherwise noted)

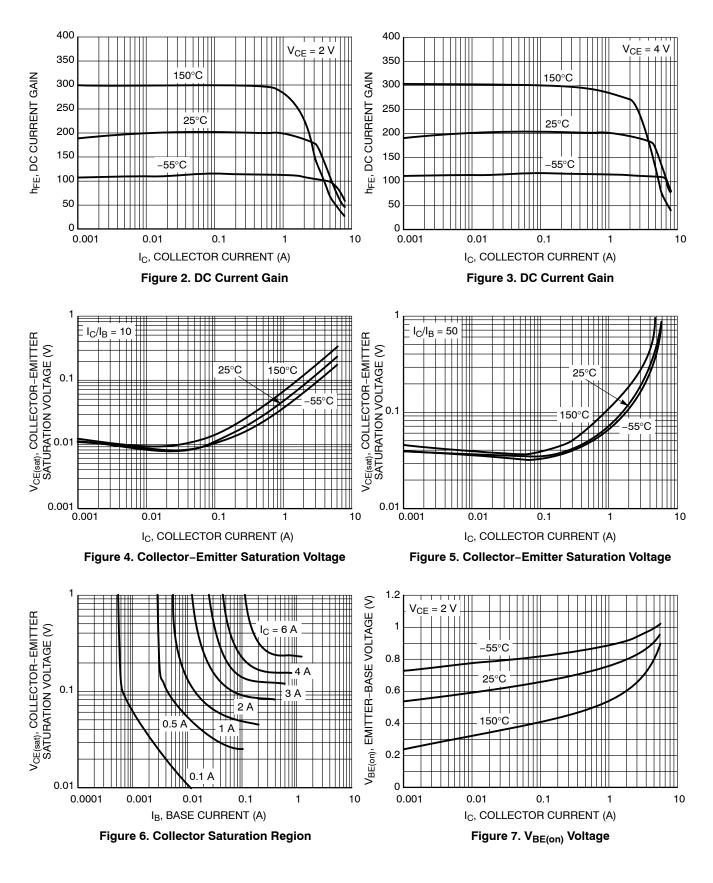
Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage $(I_C = 10 \text{ mAdc}, I_B = 0)$	V <sub>(BR)CEO</sub>	60	-	_	Vdc
Collector – Base Breakdown Voltage $(I_{C} = 0.1 \text{ mAdc}, I_{E} = 0)$	V <sub>(BR)CBO</sub>	100	-	-	Vdc
Emitter – Base Breakdown Voltage $(I_E = 0.1 \text{ mAdc}, I_C = 0)$	V <sub>(BR)EBO</sub>	6.0	-	_	Vdc
Collector Cutoff Current (V <sub>CB</sub> = 100 Vdc, I <sub>E</sub> = 0)	I <sub>CBO</sub>	_	-	0.1	μAdc
Emitter Cutoff Current (V <sub>EB</sub> = 6.0 Vdc)	I <sub>EBO</sub>	-	-	0.1	μAdc
ON CHARACTERISTICS					
DC Current Gain (Note 4) ( $I_C = 500 \text{ mA}, V_{CE} = 2.0 \text{ V}$ ) ( $I_C = 1.0 \text{ A}, V_{CE} = 2.0 \text{ V}$ ) ( $I_C = 2.0 \text{ A}, V_{CE} = 2.0 \text{ V}$ ) ( $I_C = 6.0 \text{ A}, V_{CE} = 2.0 \text{ V}$ )	h <sub>FE</sub>	150 120 100 50	- - - -	 360 	-
Collector – Emitter Saturation Voltage (Note 4) ( $I_C = 0.1 A$ , $I_B = 2.0 mA$ ) ( $I_C = 1.0 A$ , $I_B = 0.100 A$ ) ( $I_C = 2.0 A$ , $I_B = 0.200 A$ ) ( $I_C = 3.0 A$ , $I_B = 60 mA$ ) ( $I_C = 6.0 A$ , $I_B = 0.6 A$ )	V <sub>CE(sat)</sub>	- - - - -	_ 0.045 0.085 _ _	0.040 0.060 0.100 0.220 0.300	V
Base – Emitter Saturation Voltage (Note 4) $(I_C = 1.0 \text{ A}, I_B = 0.1 \text{ A})$	V <sub>BE(sat)</sub>	_	_	0.900	V
Base – Emitter Turn–on Voltage (Note 4) (I <sub>C</sub> = 1.0 A, V <sub>CE</sub> = 2.0 V)	V <sub>BE(on)</sub>	-	-	0.900	V
Cutoff Frequency ( $I_C = 500 \text{ mA}, V_{CE} = 10 \text{ V}, f = 1.0 \text{ MHz}$ )	f <sub>T</sub>	100	-	-	MHz
Input Capacitance (V <sub>EB</sub> = 5.0 V, f = 1.0 MHz)	Cibo	-	400	-	pF
Output Capacitance (V <sub>CB</sub> = 10 V, f = 1.0 MHz)	Cobo	-	37	-	pF
SWITCHING CHARACTERISTICS					
Delay (V <sub>CC</sub> = 30 V, I <sub>C</sub> = 750 mA, I <sub>B1</sub> = 15 mA)	t <sub>d</sub>	-	85	-	ns
Rise ( $V_{CC}$ = 30 V, $I_{C}$ = 750 mA, $I_{B1}$ = 15 mA)	t <sub>r</sub>	-	115	-	ns
Storage (V <sub>CC</sub> = 30 V, $I_C$ = 750 mA, $I_{B1}$ = 15 mA)	t <sub>s</sub>	-	1350	-	ns
Fall (V <sub>CC</sub> = 30 V, I <sub>C</sub> = 750 mA, I <sub>B1</sub> = 15 mA)	t <sub>f</sub>	_	125	-	ns

Fall (V<sub>CC</sub> = 30 V, I<sub>C</sub> = 750 mA, I<sub>B1</sub> = 15 mA) 4. Pulsed Condition: Pulse Width = 300 msec, Duty Cycle  $\leq 2\%$ .

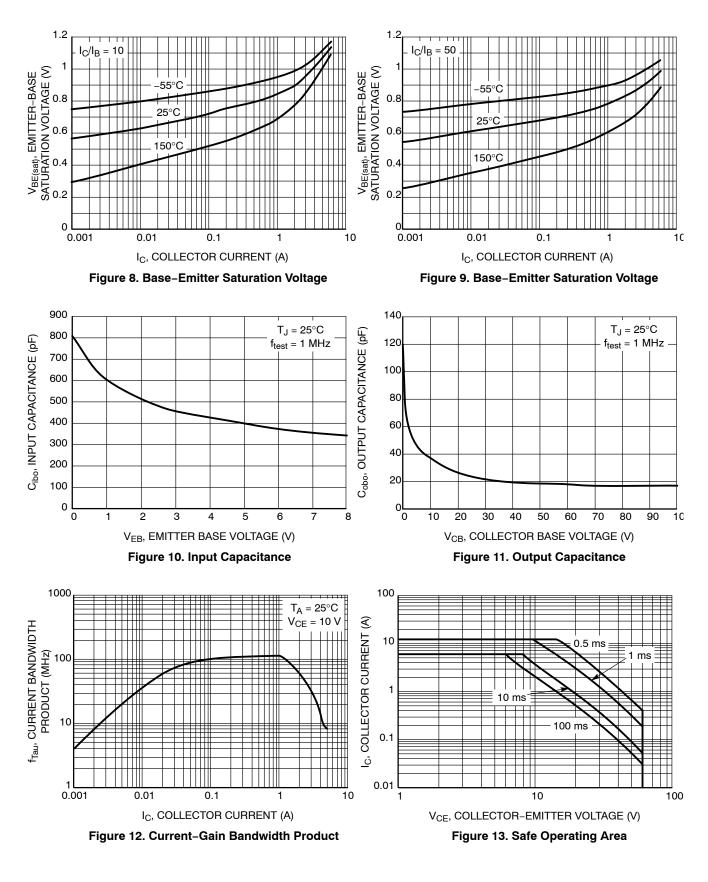


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### **TYPICAL CHARACTERISTICS**



## **TYPICAL CHARACTERISTICS**



DATE 02 OCT 2018

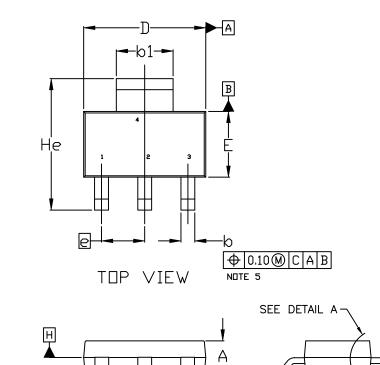




SCALE 1:1

0.10 C

A1



11

SIDE VIEW

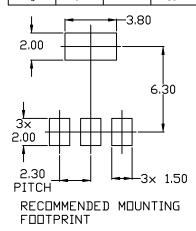
DETAIL A

NDTES:

SOT-223 (TO-261) CASE 318E-04 ISSUE R

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. DIMENSIONS D & E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.200MM PER SIDE.
- 4. DATUMS A AND B ARE DETERMINED AT DATUM H.
- 5. AI IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY.
- 6. POSITIONAL TOLERANCE APPLIES TO DIMENSIONS 6 AND 61.

	MILLIMETERS			
DIM	MIN.	NDM.	MAX.	
A	1.50	1.63	1.75	
A1	0.02	0.06	0.10	
b	0.60	0.75	0.89	
b1	2.90	3.06	3.20	
с	0.24	0.29	0.35	
D	6.30	6.50	6.70	
E	3.30	3.50	3.70	
e	2.30 BSC			
L	0.20			
L1	1.50	1.75	2.00	
He	6.70	7.00	7.30	
θ	0*		10*	



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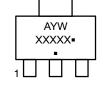
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#### SOT-223 (TO-261) CASE 318E-04 ISSUE R

#### DATE 02 OCT 2018

STYLE 1: PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR	STYLE 2: PIN 1. ANODE 2. CATHODE 3. NC 4. CATHODE	STYLE 3: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN	STYLE 4: PIN 1. SOURCE 2. DRAIN 3. GATE 4. DRAIN	STYLE 5: PIN 1. DRAIN 2. GATE 3. SOURCE 4. GATE
STYLE 6: PIN 1. RETURN 2. INPUT 3. OUTPUT 4. INPUT	STYLE 7: PIN 1. ANODE 1 2. CATHODE 3. ANODE 2 4. CATHODE	STYLE 8: CANCELLED	STYLE 9: PIN 1. INPUT 2. GROUND 3. LOGIC 4. GROUND	STYLE 10: PIN 1. CATHODE 2. ANODE 3. GATE 4. ANODE
STYLE 11: PIN 1. MT 1 2. MT 2 3. GATE 4. MT 2	STYLE 12: PIN 1. INPUT 2. OUTPUT 3. NC 4. OUTPUT	STYLE 13: PIN 1. GATE 2. COLLECTOR 3. EMITTER 4. COLLECTOR		

# GENERIC MARKING DIAGRAM\*



- A = Assembly Location
- Y = Year
- W = Work Week
- XXXXX = Specific Device Code
- = Pb-Free Package
- (Note: Microdot may be in either location) \*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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